

■ ⚠Caution (Rating)

1. Do not use products beyond the rated current as this may create excessive heat and deteriorate the insulation resistance.
2. Be sure to provide an appropriate fail-safe function on your product to prevent a second damage that may be caused by the abnormal function or the failure our product.

■ ⚠Caution (Soldering and Mounting)

1. Self-heating

Please provide special attention when mounting chip "EMIFIL" (BLM_P) series in close proximity to other products that radiate heat.
The heat generated by other products may deteriorate the insulation resistance and cause excessive heat in this component.

■ Notice (Storage and Operating Condition)

< Operating Environment >

Do not use products in a chemical atmosphere such as chlorine gas, acid or sulfide gas.

< Storage and Handling Requirements >

1. Storage Period

BLM series should be used within 6 months.
Products to be used after this period should be checked for solderability or bondability with glue.

2. Storage Conditions

(1) Storage temperature: -10 to +40 degrees C

Relative humidity: 15 to 85%

Avoid sudden changes in temperature and humidity.

(2) Do not store products in a chemical atmosphere such as chlorine gas, acid or sulfide gas.

■ Notice (Soldering and Mounting)

1. Washing

Failure and degradation of a product are caused by the washing method. When you wash in conditions that are not in mounting information, please contact Murata engineering.

2. Soldering

Reliability decreases with improper soldering methods. Please solder by the standard soldering conditions shown in mounting information.

3. Mounting on-board with Conductive Glue

BLM18AG_WH is designed for conductive glue mounting method. Please refer to Mounting information.

4. Other

Noise suppression levels resulting from Murata's EMI suppression filters "EMIFIL" may vary, depending on the circuits and ICs used, type of noise, mounting pattern, mounting location, and other operating conditions. Be sure to check and confirm in advance the noise suppression effect of each filter, in actual circuits, etc. before applying the filter in a commercial-purpose equipment design.

■ Notice (Handling)

1. Resin Coating

It may affect the product's performance when using resin for coating/ molding products.

So please pay careful attention in selecting resin.

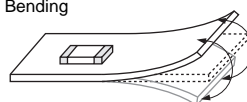
Prior to use, please evaluate reliability with the product mounted in your application set.

2. Handling of a Substrate

After mounting products on a substrate, do not apply any stress to the product caused by bending or twisting to the substrate when cropping the substrate, inserting and removing a connector from the substrate or tightening screw to the substrate.

Excessive mechanical stress may cause cracking in the Product.

Bending



Twisting

